

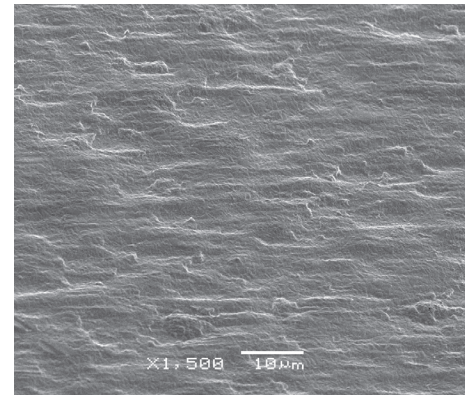
Superior adhesion electrodeposited copper foil.

Applications:

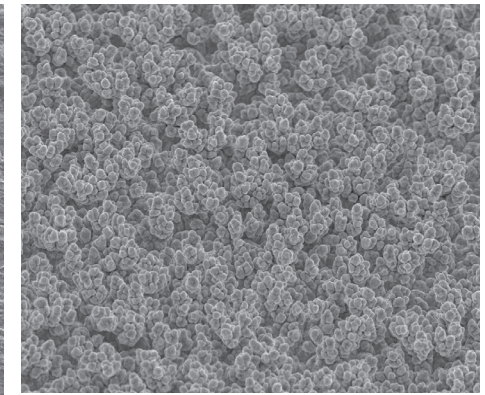
- PCB outer layers

Features:

- IPC Grade III
- Increased roughening treatment on matte side of foil
- Excellent adhesion to a wide range of resin systems



Untreated Drum Side
H oz. /18 μm (1500x)



Treated Matte Side
H oz. /18 μm (1500x)

Typical Values:

Attribute		Unit	Value		Reference
Thickness Designation			T	H	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		μm	12	18	
		oz.	3/8	1/2	
Area Weight		g/m ²	106.8	152.5	
		g/254 in ²	17.5	25	
		oz./ft ²	0.375	0.5	
Roughness	Drum Side Ra	μm	0.25		IPC-TM-650-2.2.17
		μ"	10		
	Matte Side Rz	μm	6.4	7.6	
		μ"	250	300	
Tensile	Ambient	Kg/mm ²	42		IPC-TM-650-2.4.18
		Kpsi	60		
	180°C	Kg/mm ²	21		
		Kpsi	30		
Elongation	Ambient	%	6	8	
	180°C	%	8		
Peel Strength* (Matte/Treated Side)	Cond. B	Kg/cm	1.5	1.8	IPC-TM-650-2.4.8
		Lbs/in	8.5	10	

* Peel strength measured on 170°C Tg Epoxy

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